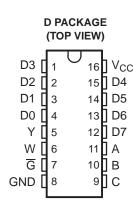
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8-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER

FEATURES

- Qualified for Automotive Applications
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive up to 10 LSTTL Loads
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- 8-Line to 1-Line Multiplexers Can Perform as:
 - Boolean-Function Generators
 - Parallel-to-Serial Converters
 - Data Source Selectors



DESCRIPTION/ORDERING INFORMATION

This data selector/multiplexer provides full binary decoding to select one of eight data sources. The strobe (\overline{G}) input must be at a low logic level to enable the inputs. A high level at the strobe terminal forces the W output high and the Y output low.

ORDERING INFORMATION(1)

T _A	PACK	(AGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
-40°C to 125°C	SOIC - D	Reel of 2500	SN74HC151QDRQ1	HC151Q	

⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

FUNCTION TABLE

	I	OUTP	UTS ⁽¹⁾		
	SELECT		STROBE	Υ	W
С	В	Α	G	I	VV
Х	Χ	Χ	Н	L	Н
L	L	L	L	D0	D0
L	L	Н	L	D1	D1
L	Н	L	L	D2	D2
L	Н	Н	L	D3	D3
Н	L	L	L	D4	D4
Н	L	Н	L	D5	D5
Н	Н	L	L	D6	D6
Н	Н	Н	L	D7	D7

(1) D0, D1 . . . D7 = the level of the respective D input

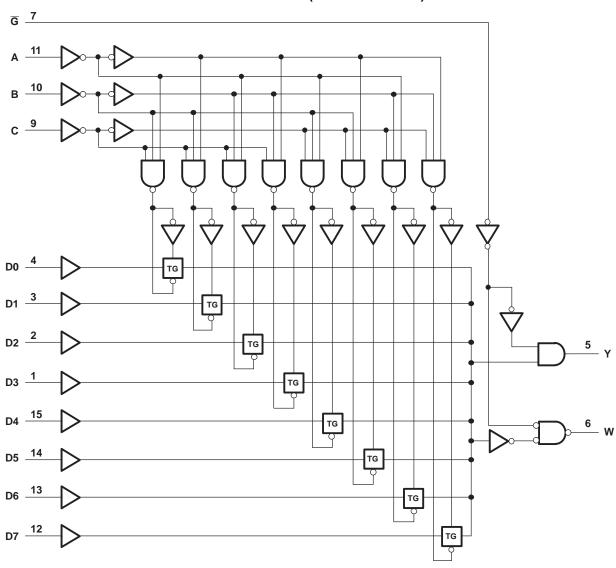


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

⁽²⁾ Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



LOGIC DIAGRAM (POSITIVE LOGIC)





Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	7	V
I _{IK}	Input clamp current	$V_{I} < 0 \text{ or } V_{I} > V_{CC}^{(2)}$		±20	mA
I _{OK}	Output clamp current	$V_{O} < 0 \text{ or } V_{O} > V_{CC}^{(2)}$		±20	mA
Io	Continuous output current	$V_{O} = 0$ to V_{CC}		±35	mA
	Continuous current through V _{CC} or GND			±70	mA
θ_{JA}	Package thermal impedance (3)			73	°C/W
T _{stg}	Storage temperature range		-65	150	°C
		Human-body model		2	kV
	ESD rating	Charged-device model		1	kV
		Machine model		200	V

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions⁽¹⁾

			MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage		2	5	6	V
		V _{CC} = 2 V	1.5			
V_{IH}	High-level input voltage	V _{CC} = 4.5 V	3.15			V
		V _{CC} = 6 V	4.2			
		V _{CC} = 2 V			0.5	
V_{IL}	Low-level input voltage			1.35	V	
		V _{CC} = 6 V			1.8	
VI	Input voltage	,	0		V_{CC}	V
Vo	Output voltage		0		V_{CC}	V
		V _{CC} = 2 V			1000	
$\Delta t/\Delta v$	Input transition rise/fall time	V _{CC} = 4.5 V			500	ns
		V _{CC} = 6 V			400	
T _A	Operating free-air temperature	<u> </u>	-40		125	°C

⁽¹⁾ All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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⁽²⁾ The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ The package thermal impedance is calculated in accordance with JESD 51-7.



Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST	TEST CONDITIONS		Т	_A = 25°C	;	MIN	MAX	UNIT
PARAMETER	1531	CONDITIONS	V _{cc}	MIN	TYP	MAX	IVIIIN	WAX	Oitii
			2 V	1.9	1.998		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		
V_{OH}	$V_I = V_{IH}$ or V_{IL}		6 V	5.9	5.999		5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	98 4.3		3.7		
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2		
			2 V		0.002	0.1		0.1	
		$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1	
V_{OL}	$V_I = V_{IH}$ or V_{IL}		6 V		0.001	0.1		0.1	V
		I _{OL} = 6 mA	4.5 V		0.17	0.26		0.4	
		I _{OL} = 7.8 mA	6 V		0.15	0.26		0.4	
I _I	$V_I = V_{CC}$ or 0		6 V		±0.1	±100	Ė	±1000	nA
I _{CC}	$V_I = V_{CC}$ or 0,	I _O = 0	6 V			8		160	μΑ
C _i			2 V to 6 V		3	10		10	pF

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то		T _A = 25°C	;	BAINI BAAY	UNIT
PARAMETER	(INPUT)	(OUTPUT)	V _{CC}	MIN TYP	MAX	MIN MAX	
			2 V	94	250	360	
	A, B, or C	Y or W 4.5 V 30 50	73				
			6 V	25	43	62	
			2 V 74 195 283 W 4.5 V 23 39 57				
t _{pd}	Any D	Y or W		23	39	57	ns
			6 V	20	33	48	
		Y or W	2 V	49	127	185	
	G		4.5 V	15	25	37	
			6 V	13	22	32	
			2 V	22	75	110	
t _t		Y or W	4.5 V	9	15	22	ns
			6 V	8	13	19	

Operating Characteristics

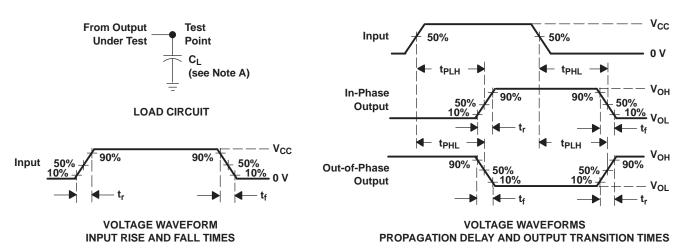
 $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load	70	pF

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f = 6 \text{ ns.}$
- C. The outputs are measured one at a time, with one input transition per measurement.
- D. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC151QDRQ1	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC151Q	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74HC151-Q1:



PACKAGE OPTION ADDENDUM

10-Dec-2020

• Catalog: SN74HC151

Military: SN54HC151

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

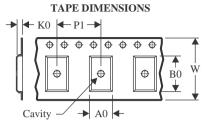
• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC151QDRQ1	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 10-Aug-2022

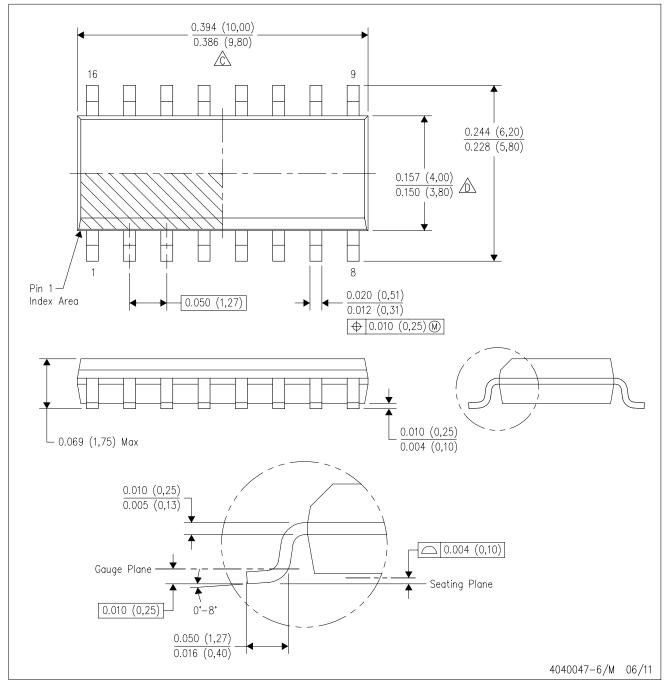


*All dimensions are nominal

Ì	Device	Device Package Type		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	SN74HC151QDRQ1	SOIC	D	16	2500	356.0	356.0	35.0

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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